

STARPOWER

SEMICONDUCTOR

IGBT

GD600HTA120P6HL

1200V/600A 6 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as hybrid and electric vehicle.

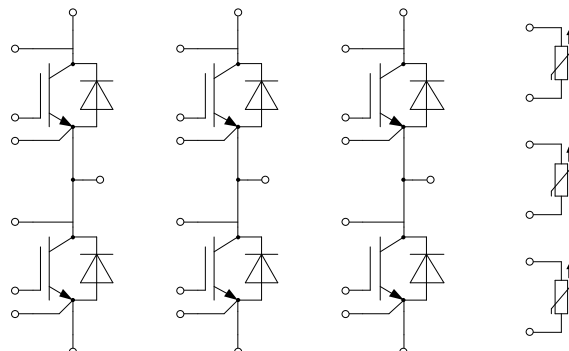
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching losses
- 6 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper pinfin baseplate using Si₃N₄AMB technology

Typical Applications

- Automotive application
- Hybrid and electric vehicle
- Inverter for motor drive

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_F=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Values	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_{CN}	Implemented Collector Current	600	A
I_C	Collector Current @ $T_F=85^{\circ}\text{C}$	450	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	1200	A
P_D	Maximum Power Dissipation @ $T_F=75^{\circ}\text{C}$ $T_j=175^{\circ}\text{C}$	970	W

Diode

Symbol	Description	Values	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_{FN}	Implemented Collector Current	600	A
I_F	Diode Continuous Forward Current	450	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	1200	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature continuous For 10s within a period of 30s, occurrence maximum 3000 times over lifetime	-40 to +150 +150 to +175	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
d_{Creep}	Terminal to Heatsink Terminal to Terminal	9.0 9.0	mm
d_{Clear}	Terminal to Heatsink Terminal to Terminal	4.5 4.5	mm

IGBT Characteristics $T_F=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=450\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.40		V	
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		1.65			
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_j=175^{\circ}\text{C}$		1.70			
		$I_C=600\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.60			
		$I_C=600\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		1.90			
		$I_C=600\text{A}, V_{GE}=15\text{V}, T_j=175^{\circ}\text{C}$		2.00			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=15.6\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$		6.4		V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			1.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA	
R_{Gint}	Internal Gate Resistance			1.67		Ω	
C_{ies}	Input Capacitance			81.2		nF	
C_{oes}	Output Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		1.56		nF	
C_{res}	Reverse Transfer Capacitance			0.53		nF	
Q_G	Gate Charge	$V_{CE}=600\text{V}, I_C=600\text{A}, V_{GE}=-8\dots+15\text{V}$		5.34		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=600\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=2.2\Omega, L_S=22\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_j=25^{\circ}\text{C}$		290		ns	
t_r	Rise Time			81		ns	
$t_{d(off)}$	Turn-Off Delay Time			895		ns	
t_f	Fall Time			87		ns	
E_{on}	Turn-On Switching Loss			53.5		mJ	
E_{off}	Turn-Off Switching Loss			47.5		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=600\text{V}, I_C=600\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=2.2\Omega, L_S=22\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_j=150^{\circ}\text{C}$		322		ns
t_r	Rise Time				103		ns
$t_{d(off)}$	Turn-Off Delay Time				1017		ns
t_f	Fall Time				171		ns
E_{on}	Turn-On Switching Loss			84.2		mJ	
E_{off}	Turn-Off Switching Loss			63.7		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=600\text{A}, R_{Gon}=1.0\Omega, R_{Goff}=2.2\Omega, L_S=22\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_j=175^{\circ}\text{C}$			334		ns
t_r	Rise Time				104		ns
$t_{d(off)}$	Turn-Off Delay Time				1048		ns
t_f	Fall Time				187		ns
E_{on}	Turn-On Switching Loss			89.8		mJ	
E_{off}	Turn-Off Switching Loss			65.4		mJ	
I_{SC}	SC Data		$t_p \leq 6\mu\text{s}, V_{GE}=15\text{V}$		2000		A

$T_j=175^{\circ}\text{C}, V_{CC}=800\text{V},$ $V_{CEM}\leq 1200\text{V}$
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Diode Characteristics $T_f=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=450\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.80		V
		$I_F=450\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.75		
		$I_F=450\text{A}, V_{GE}=0\text{V}, T_j=175^{\circ}\text{C}$		1.70		
		$I_F=600\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.95		
		$I_F=600\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.95		
		$I_F=600\text{A}, V_{GE}=0\text{V}, T_j=175^{\circ}\text{C}$		1.90		
Q_r	Recovered Charge			22.5		μC
I_{RM}	Peak Reverse Recovery Current	$V_R=600\text{V}, I_F=600\text{A},$ $-di/dt=7040\text{A}/\mu\text{s}, V_{GE}=-8\text{V}$ $L_S=22\text{nH}, T_j=25^{\circ}\text{C}$		304		A
E_{rec}	Reverse Recovery Energy			10.8		mJ
Q_r	Recovered Charge			46.6		μC
I_{RM}	Peak Reverse Recovery Current	$V_R=600\text{V}, I_F=600\text{A},$ $-di/dt=5790\text{A}/\mu\text{s}, V_{GE}=-8\text{V}$ $L_S=22\text{nH}, T_j=150^{\circ}\text{C}$		336		A
E_{rec}	Reverse Recovery Energy			18.2		mJ
Q_r	Recovered Charge			49.8		μC
I_{RM}	Peak Reverse Recovery Current	$V_R=600\text{V}, I_F=600\text{A},$ $-di/dt=5520\text{A}/\mu\text{s}, V_{GE}=-8\text{V}$ $L_S=22\text{nH}, T_j=175^{\circ}\text{C}$		346		A
E_{rec}	Reverse Recovery Energy			19.8		mJ

NTC Characteristics $T_f=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

Module Characteristics $T_F=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		8		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.75		m Ω
Δp	$\Delta V/\Delta t=10.0\text{dm}^3/\text{min}, T_F=75^{\circ}\text{C}$		64		mbar
p	Maximum Pressure In Cooling Circuit			2.5	bar
R_{thJF}	Junction-to-Cooling Fluid (per IGBT)		0.090	0.103	K/W
	Junction-to-Cooling Fluid (per Diode) $\Delta V/\Delta t=10.0\text{dm}^3/\text{min}, T_F=75^{\circ}\text{C}$		0.126	0.145	
M	Terminal Connection Torque, Screw M5	3.6		4.4	N.m
	Mounting Torque, Screw M4	1.8		2.2	
G	Weight of Module		750		g

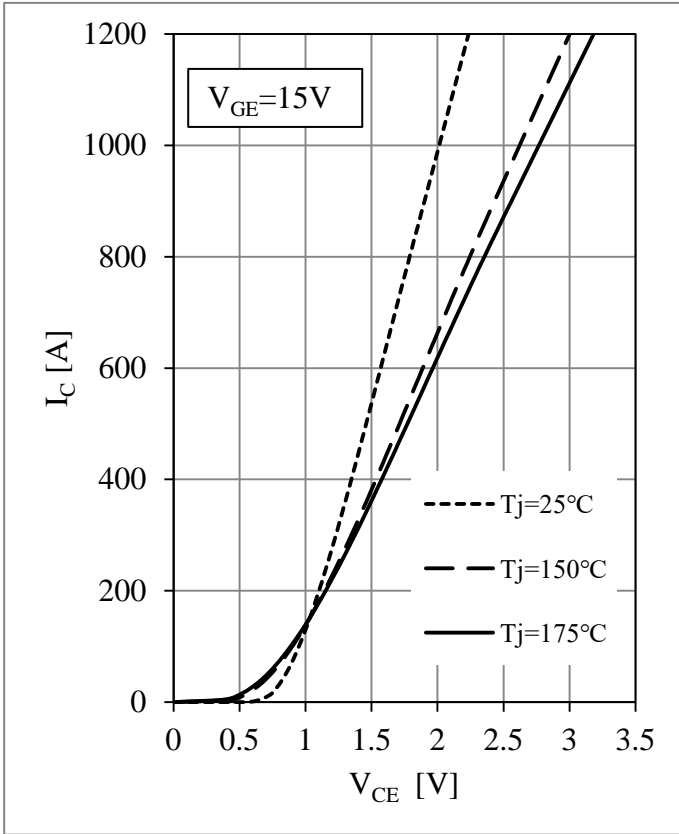


Fig 1. IGBT Output Characteristics

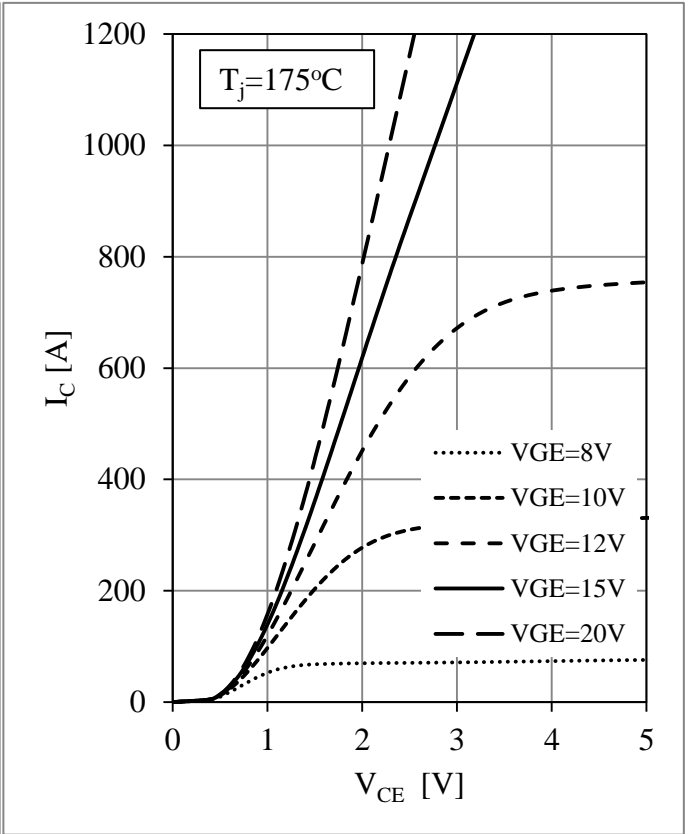


Fig 2. IGBT Output Characteristics

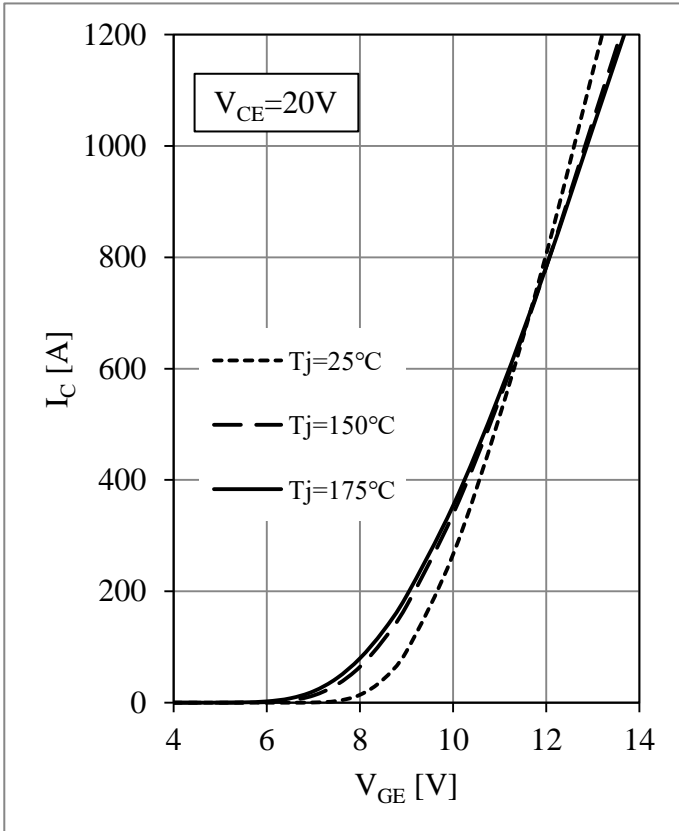


Fig 3. IGBT Transfer Characteristics

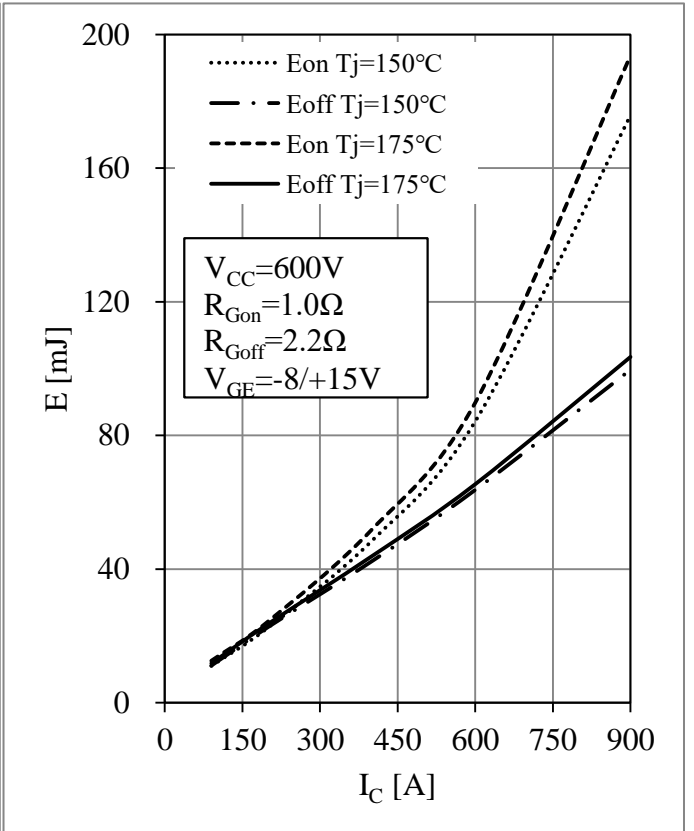


Fig 4. IGBT Switching Loss vs. I_c

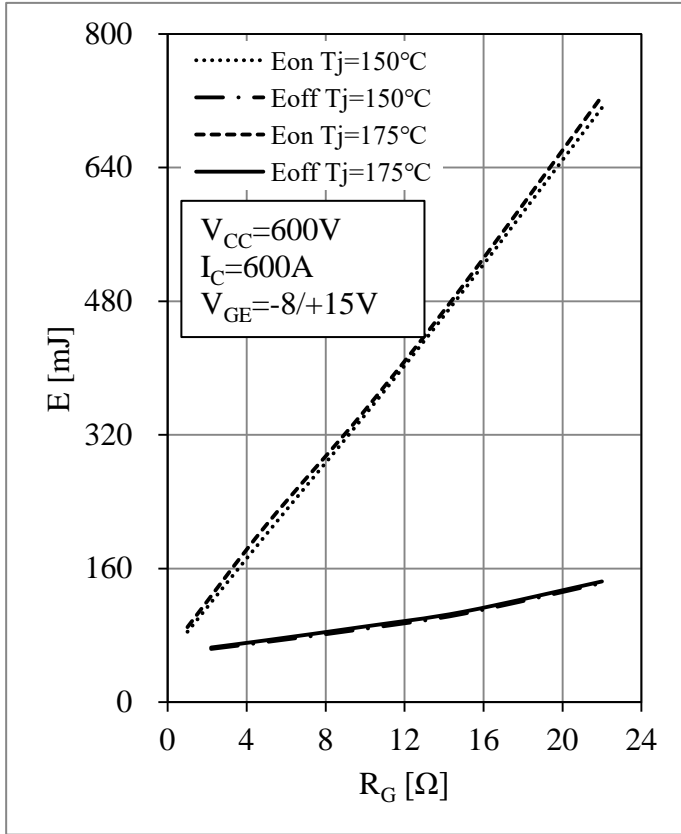


Fig 5. IGBT Switching Loss vs. R_G

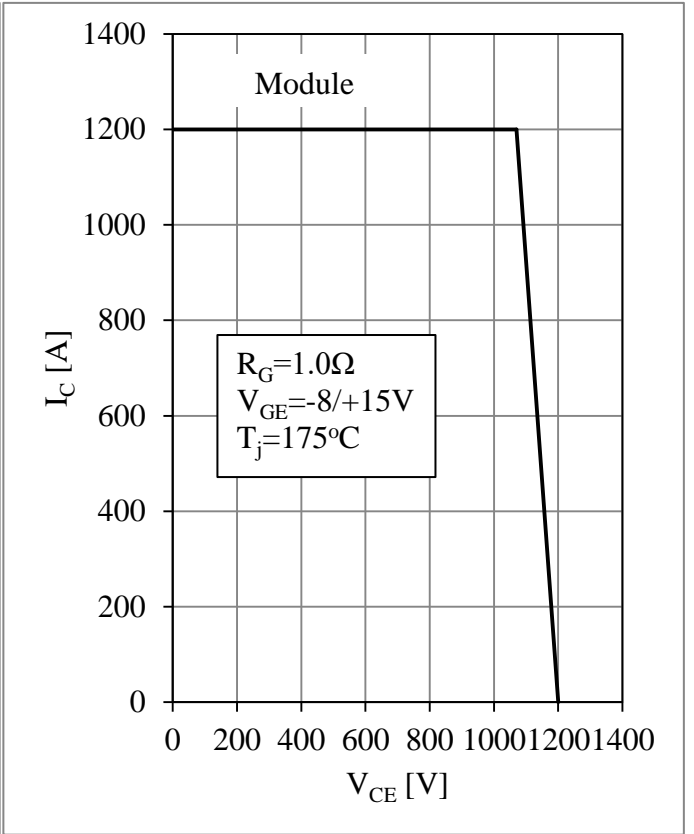


Fig 6. RBSOA

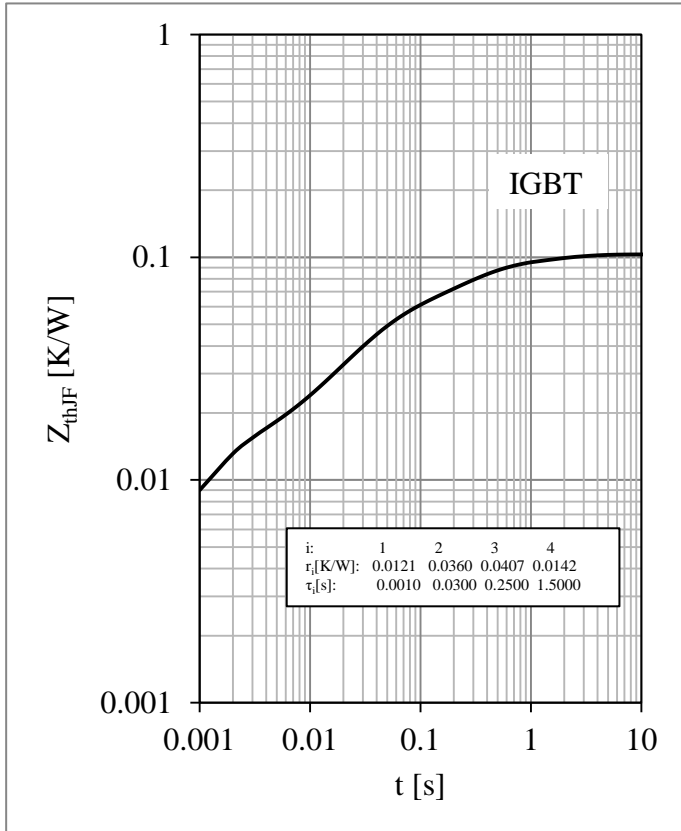


Fig 7. IGBT Transient Thermal Impedance

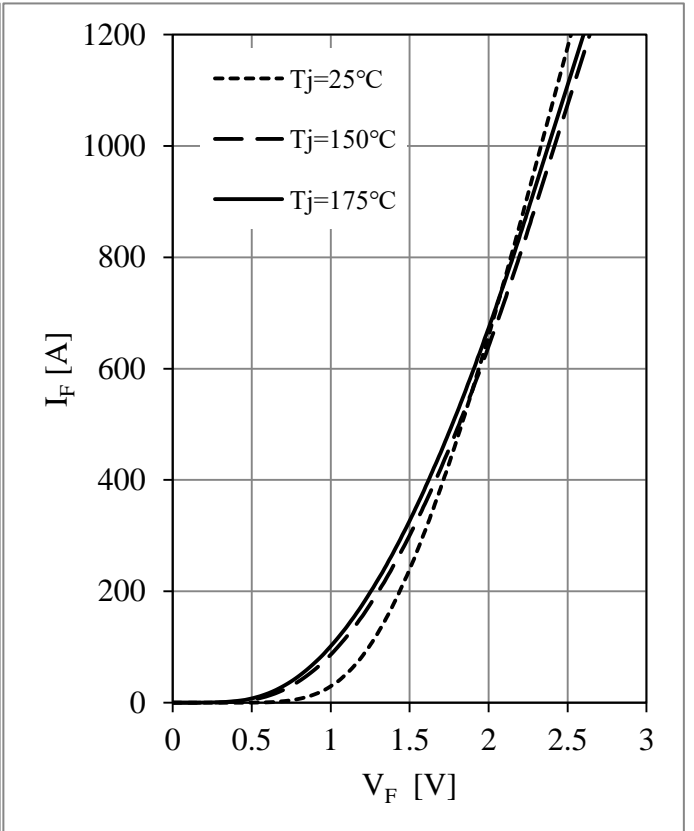


Fig 8. Diode Forward Characteristics

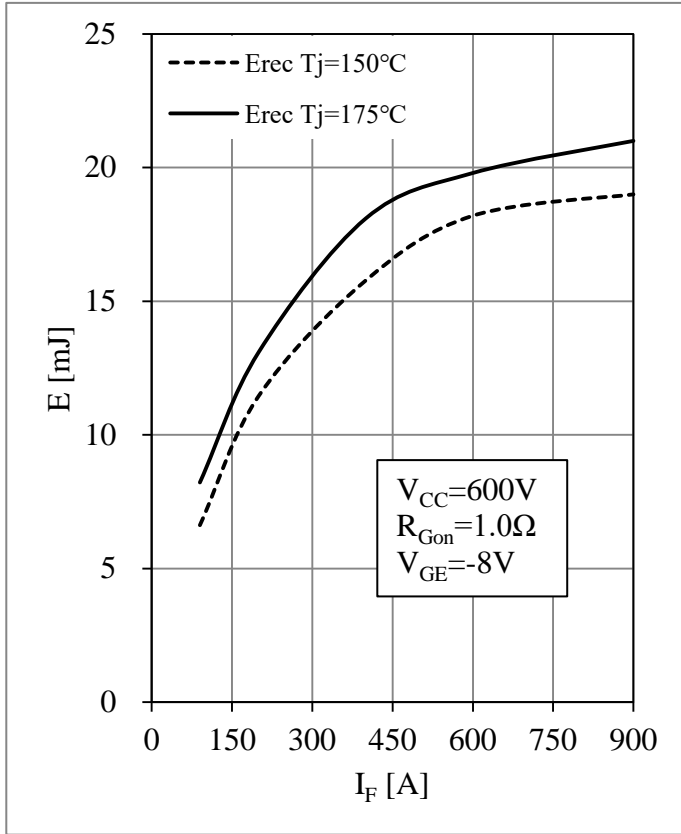


Fig 9. Diode Switching Loss vs. I_F

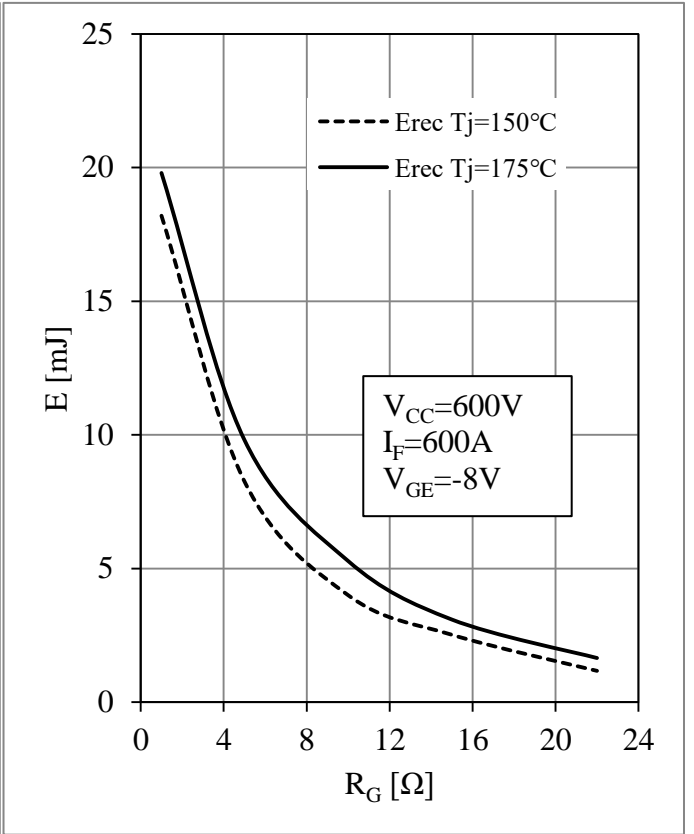


Fig 10. Diode Switching Loss vs. R_G

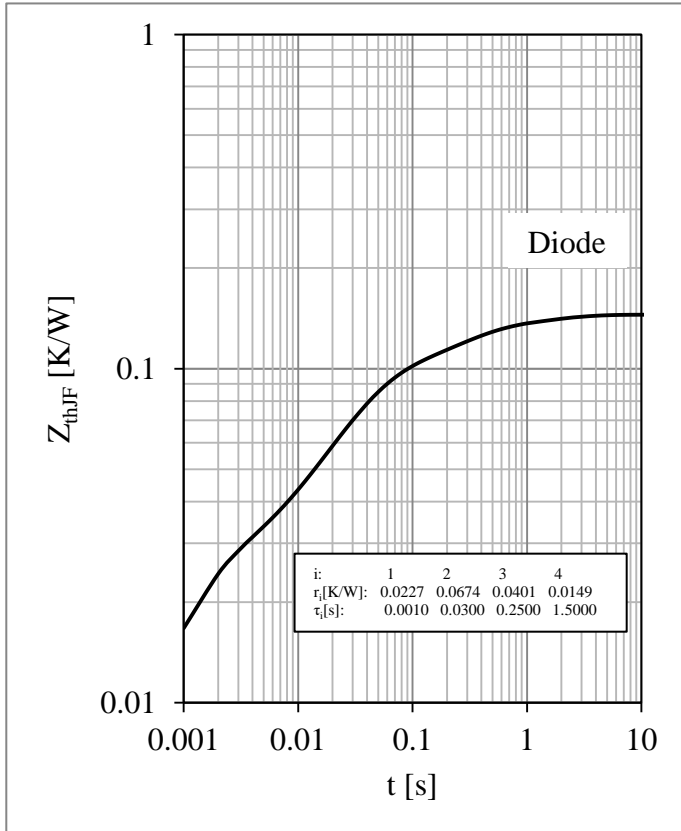


Fig 11. Diode Transient Thermal Impedance

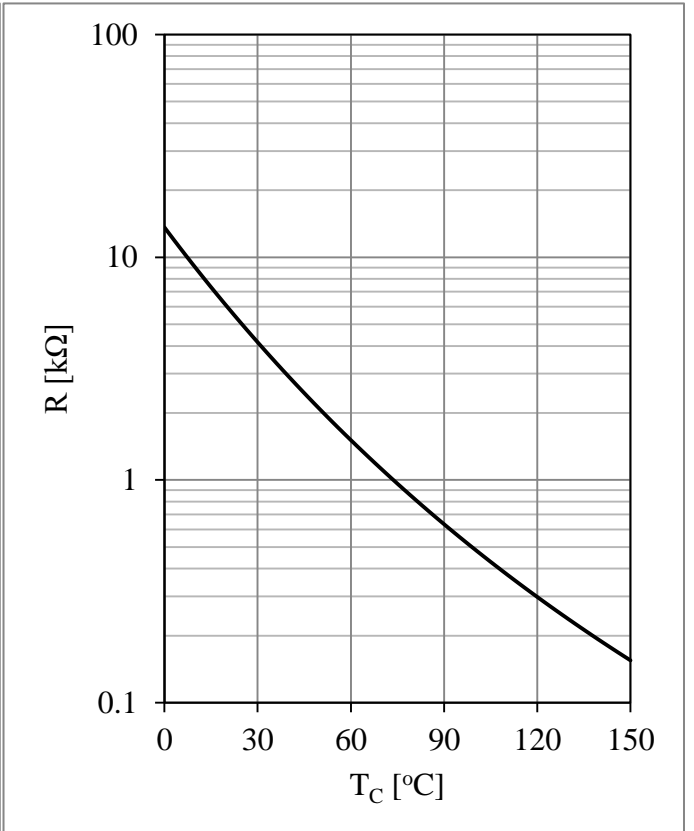


Fig 12. NTC Temperature Characteristic

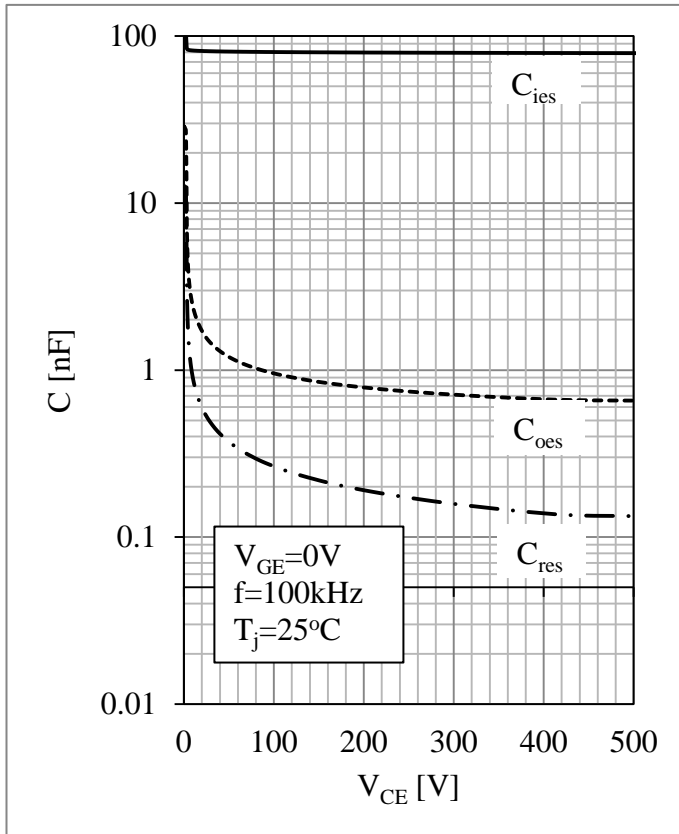


Fig 13. IGBT Capacity Characteristic

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